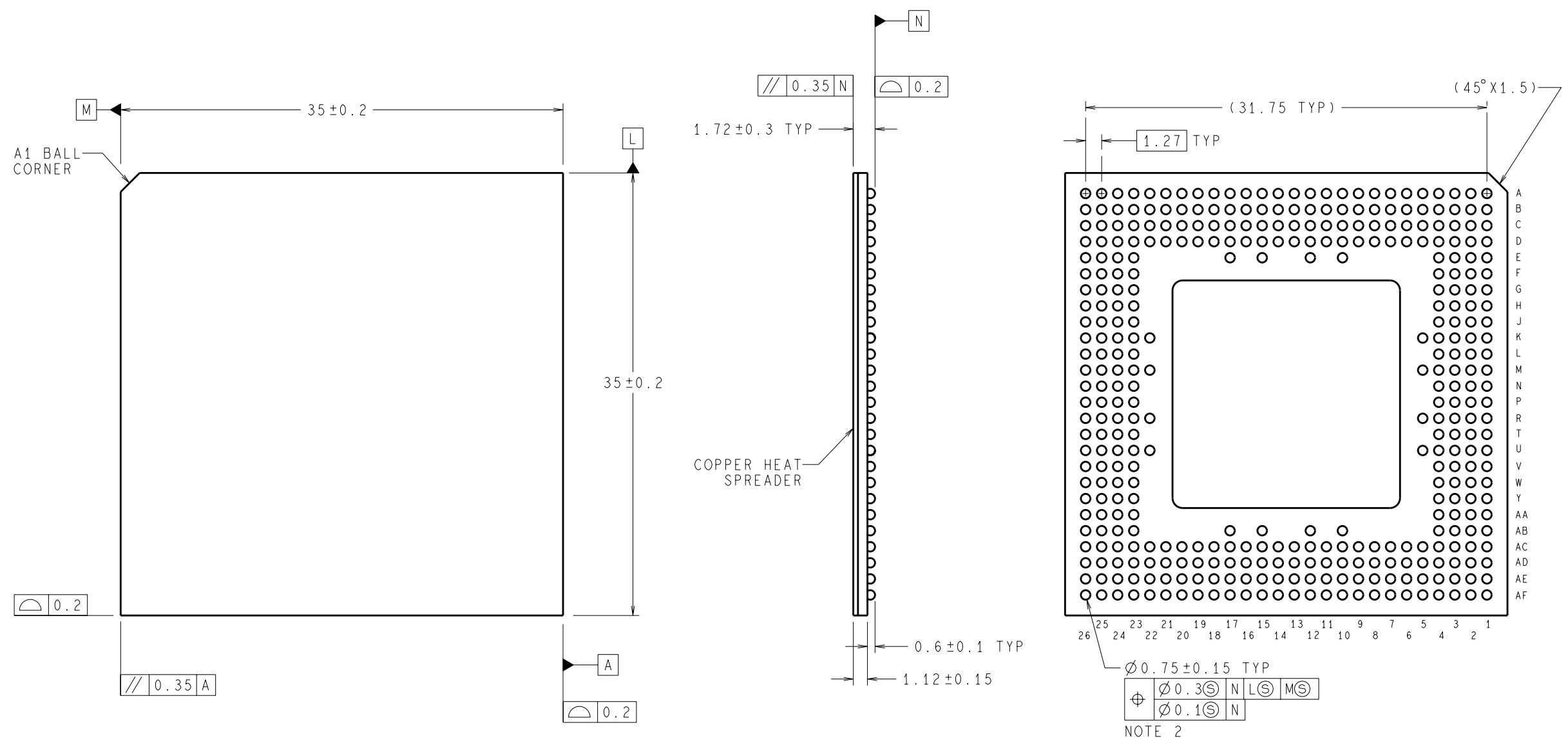


| REVISIONS | | | | |
|-----------|-----------------------------|--------|------------|----------|
| LTR | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| A | RELEASE TO DOCUMENT CONTROL | 250 | 06/07/2001 | MS/AP |



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
 2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
 3. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27.

| | | | | | |
|------------------------------|--|------------|---|-----------------|-----|
| APPROVALS | | DATE | National Semiconductor | | |
| DRAWN MARTA SUCHY | | 06/07/2001 | 2900 Semiconductor Dr., Santa Clara, CA 95052-8090 | | |
| DFTG. CHK. THANH LEQUANG | | 06/07/2001 | EBGA, 35 X 35 X 1.72mm, 368 BALL, 1.27mm PITCH | | |
| ENGR. CHK. ANINDYA PODDAR | | 06/07/2001 | | | |
| | | SCALE | SIZE | DRAWING NUMBER | REV |
| | | N/A | C | (SC)MKT-UCP368A | A |
| DO NOT SCALE DRAWING | | | | SHEET 1 of 1 | |